



Features

- For surface mounted applications in order to optimize board space
- Low profile package
- Built-in strain relief
- Glass passivated junction
- Low inductance
- Excellent clamping capability
- 3000W peak pulse power capability at 10/1000μs waveform, repetition rate (duty cycle): 0.01%
- Fast response time
- Typical IR less than 1μA above 10V



SMC
(DO-214AB)

Mechanical Data

- Case: JEDEC SMC(DO-214AB) molded plastic over glass passivated junction
- Terminals: Solderable per MIL-STD-750, Method 2026
- Polarity: Polarity symbol marking on body Mounting
- Standard Packaging: 16mm tape (EIA STD RS-481)
- Weight: 0.28g

Applications

- I/O interface
- AC/DC power supply
- Low frequency signal transmission line (RS232, RS485, etc.)

Maxmim Ratings (Ta=25°C unless otherwise noted)

Peak pulse power dissipation at 10/1000μs waveform (Note1, Note2, Fig.1)	P _{PPM}	3000	W
Peak pulse current	I _{PP}	62	A
Steady state power dissipation at T _A =50°C (Fig.5)	P _{M(AV)}	6.5	W
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load, (JEDEC Method) (Note3, Fig.6)	I _{FSM}	300	A
Operating junction and Storage Temperature Range.	T _J , T _{STG}	-65 to +150	°C
Typical thermal resistance junction to lead	R _{θJL}	15	°C/W
Typical thermal resistance junction to ambient	R _{θJA}	75	°C/W

Notes:1. Non-repetitive current pulse, per Fig.3 and derated above T_A=25°C per Fig.2.
2. Mounted on 5.0mm×5.0mm (0.03mm thick) copper pads to each terminal.
3. 8.3ms single half sine-wave, or equivalent square wave, duty cycle=4 pulses per minutes maximum.

Electrical Characteristics (Ta=25°C)

Part Number		Device Marking Code		Reverse Stand- Off Voltage	Breakdown Voltage @I _T	Test Current	Maximum Clamping Voltage @I _{PP}	Peak Pulse Current	Reverse Leakage @V _{RWM}
Unidirectional	Bidirectional	UNI	BI	V _{RWM} (V)	V _{BR} (V)	I _T (mA)	V _C (V)	I _{PP} (A)	I _R (μA)
H3.0SMCJ30A	H3.0SMCJ30CA	PFK	DFK	30.0	33.3-36.9	1	48.4	62.0	1



Ratings and Characteristic Curves ($T_A=25^\circ\text{C}$ unless otherwise noted)

Figure 1. Peak Pulse Power Rating Curve

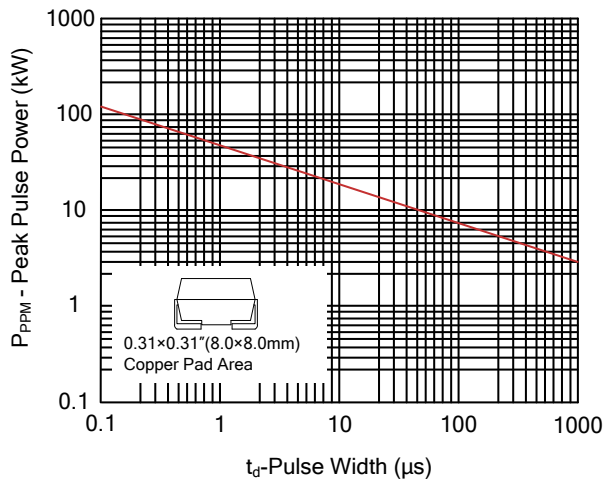


Figure 2. Pulse Derating Curve

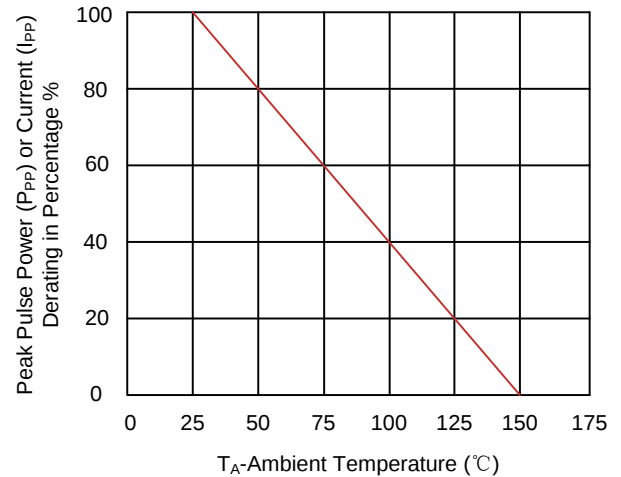


Figure 3. Pulse Waveform

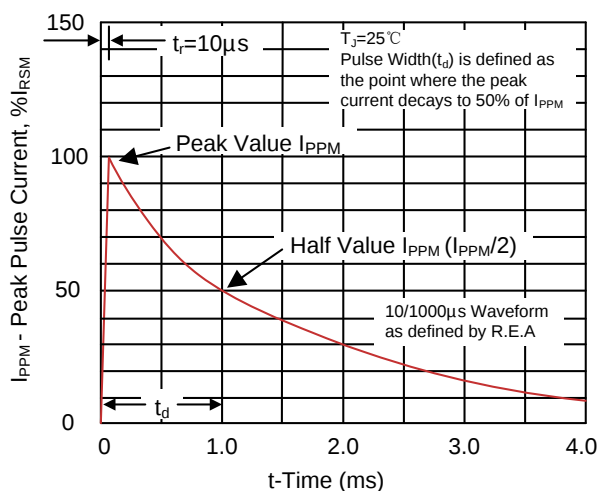


Figure 4. Typical Junction Capacitance

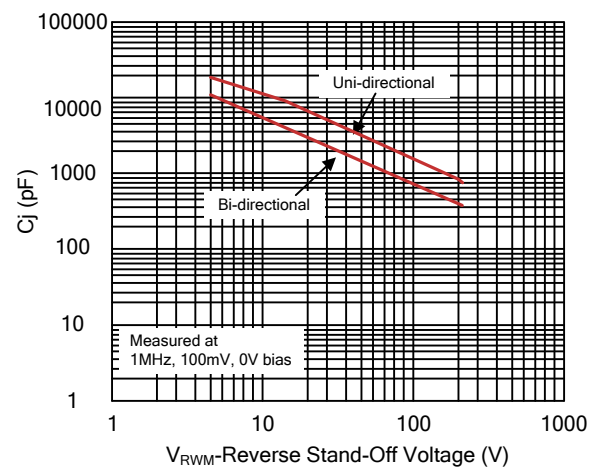


Figure 5. Steady State Power Dissipation Derating Curve

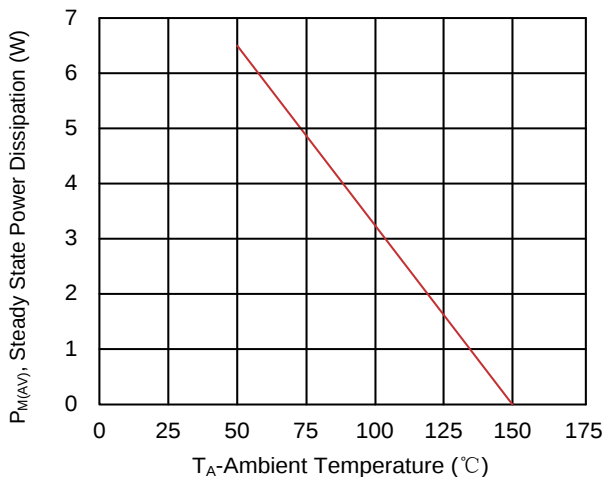
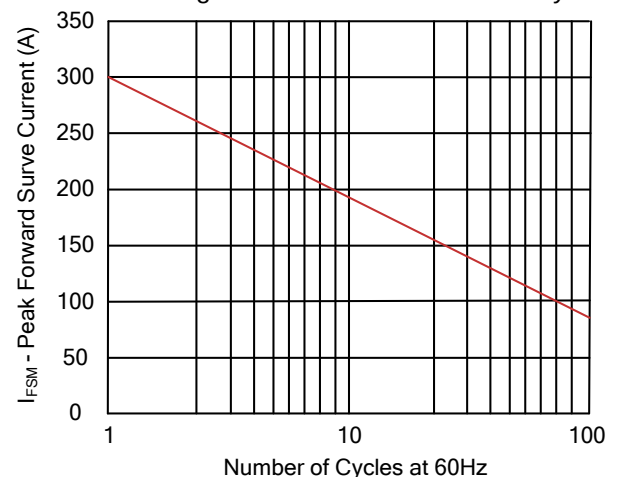
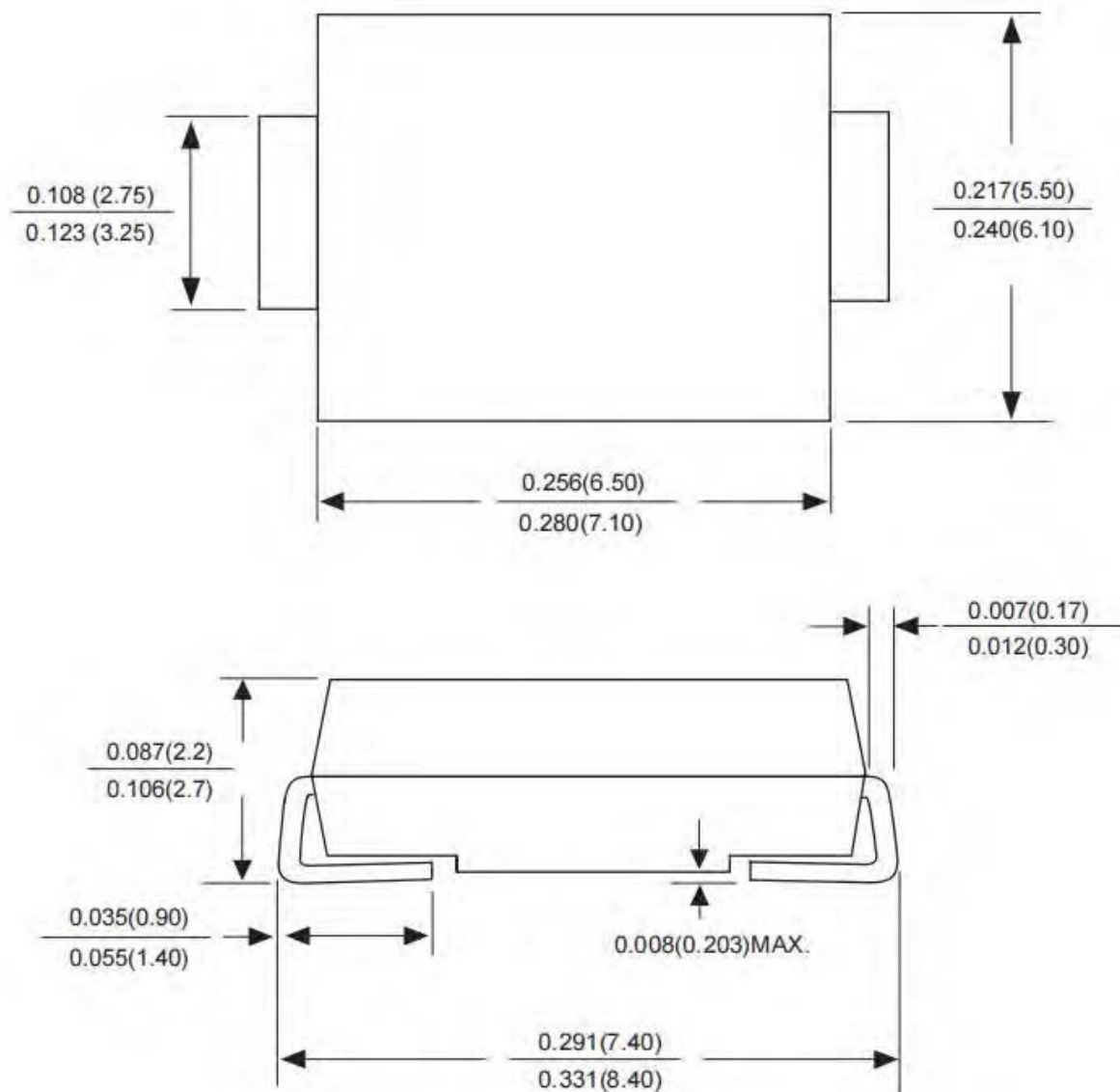


Figure 6. Maximum Non-Repetitive Forward Surge Current Uni Directional Only





Package Outline Dimensions
SMC(DO-214AB)



Dimensions in inches and (millimeters)



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